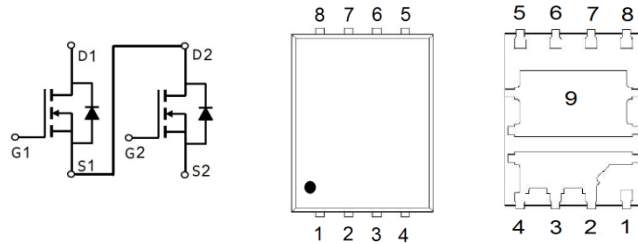




PRODUCT SUMMARY

	$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D^3
Q2	30V	9mΩ	51A
Q1	30V	16mΩ	31A



1 : G1
2,3,4 : D1
5,6,7 : S2
8 : G2
9 : S1/D2

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ °C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	Q2	Q1	UNITS
Drain-Source Voltage		V_{DS}	30	30	V
Gate-Source Voltage		V_{GS}	±20	±20	V
Continuous Drain Current ³	$T_C = 25\text{ °C}$	I_D	51	31	A
	$T_C = 100\text{ °C}$		32	20	
Pulsed Drain Current ¹		I_{DM}	100	80	
Continuous Drain Current	$T_A = 25\text{ °C}$	I_D	11	8.5	
	$T_A = 70\text{ °C}$		9	6.7	
Avalanche Current		I_{AS}	23	17	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	24	14.5	mJ
Power Dissipation	$T_C = 25\text{ °C}$	P_D	39	27	W
	$T_C = 100\text{ °C}$		15	11	
Power Dissipation	$T_A = 25\text{ °C}$	P_D	2	1.8	W
	$T_A = 70\text{ °C}$		1,3	1.1	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150		°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL		TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$R_{\theta JA}$	Q2		60	°C / W
	$R_{\theta JA}$	Q1		67	
Junction-to-Case	$R_{\theta JC}$	Q2		3.2	
	$R_{\theta JC}$	Q1		4.5	

¹Pulse width limited by maximum junction temperature $T_{J(MAX)}=150\text{ °C}$.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25\text{ °C}$. The value in any given application depends on the user's specific board design.

³Package limitation current :Q1=20A,Q2=23A

ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT	
			MIN	TYP	MAX		
STATIC							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	Q2	30		V	
			Q1	30			
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	Q2	1	1.6	3	V
			Q1	1	1.6	3	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	Q2			±100	nA
			Q1			±100	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V	Q2			1	μA
			Q1			1	
		V _{DS} = 20V, V _{GS} = 0V, T _J = 55 °C	Q2			10	
			Q1			10	
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 4.5V, I _D = 9A V _{GS} = 4.5V, I _D = 6.8A V _{GS} = 10V, I _D = 11A V _{GS} = 10V, I _D = 8.5A	Q2		9.9	14.5	mΩ
			Q1		16	25	
			Q2		7.9	9	
			Q1		12	16	
Forward Transconductance ¹	g _{fs}	V _{DS} = 5V, I _D = 11A V _{DS} = 5V, I _D = 8.5A	Q2		50		S
			Q1		36		
DYNAMIC							
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	Q2		954		pF
			Q1		535		
Output Capacitance	C _{oss}	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	Q2		124		pF
			Q1		81		
Reverse Transfer Capacitance	C _{rss}	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	Q2		104		pF
			Q1		75		
Gate Resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz	Q2		2.1		Ω
			Q1		2.3		
Total Gate Charge ²	Q _g	V _{DS} = 15V, V _{GS} = 10V, I _D = 11A V _{DS} = 15V, V _{GS} = 10V, I _D = 8.5A	Q2	V _{GS} = 10V	21.7		nC
				Q1	15.1		
			Q1	V _{GS} = 4.5V	11.5		
				Q2	8.3		
Gate-Source Charge ²	Q _{gs}	V _{DS} = 15V, V _{GS} = 10V, I _D = 8.5A	Q2		3.3		nC
Q1			2				
Gate-Drain Charge ²	Q _{gd}	V _{DS} = 15V, V _{GS} = 10V, I _D = 8.5A	Q2		5.6		nC
			Q1		5		

Turn-On Delay Time ²	$t_{d(on)}$	Q2 $V_{DS}=15V,$ $I_D=11A, V_{GS}=10V, R_{GEN}=6\Omega$ Q1 $V_{DS}=15V,$ $I_D=8.5A, V_{GS}=10V, R_{GEN}=6\Omega$	Q2		24		nS
			Q1		20		
Rise Time ²	t_r		Q2		16		
			Q1		16		
Turn-Off Delay Time ²	$t_{d(off)}$		Q2		44		
			Q1		53		
Fall Time ²	t_f		Q2		23		
			Q1		33		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$)							
Continuous Current ³	I_S		Q2			51	A
			Q1			31	
Forward Voltage ¹	V_{SD}	$I_F = 11A, V_{GS} = 0V$ $I_F = 8.5A, V_{GS} = 0V$	Q2			1.2	V
			Q1			1	
Reverse Recovery Time	t_{rr}	Q2 $I_F = 11A, dl_F/dt = 100A / \mu S$ Q1 $I_F = 8.5A, dl_F/dt = 100A / \mu S$	Q2			17	nS
			Q1			15	
Reverse Recovery Charge	Q_{rr}		Q2			7	nC
			Q1			5.6	

¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

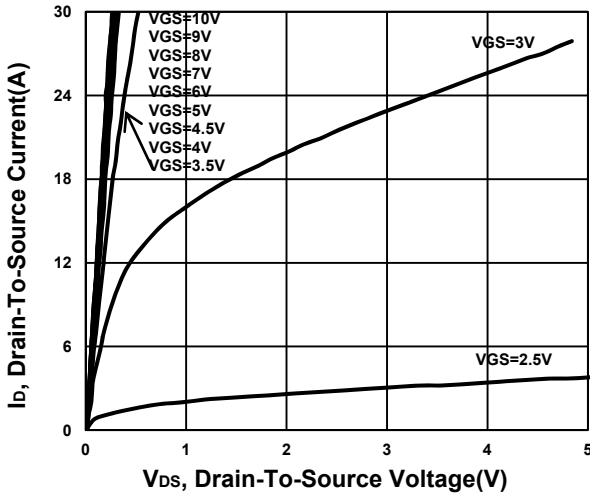
²Independent of operating temperature.

³Package limitation current : Q1=20A, Q2=23A

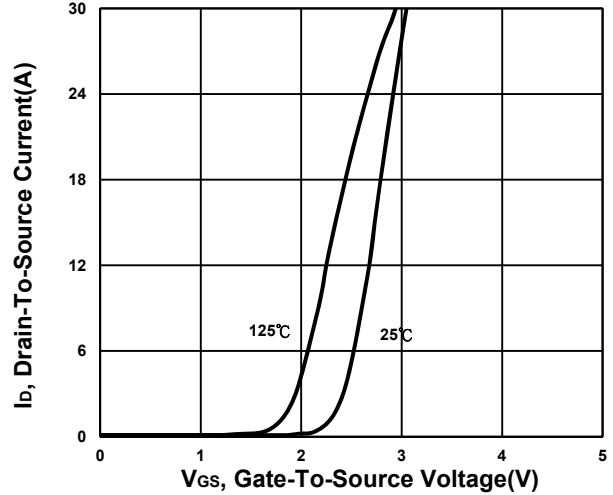
TYPICAL PERFORMANCE CHARACTERISTICS

Q2

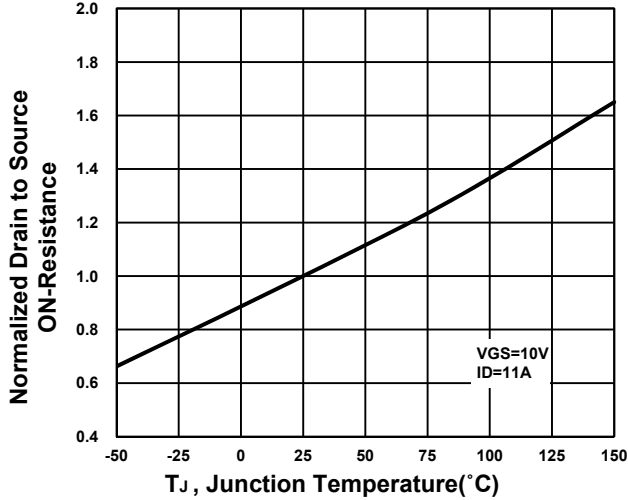
Output Characteristics



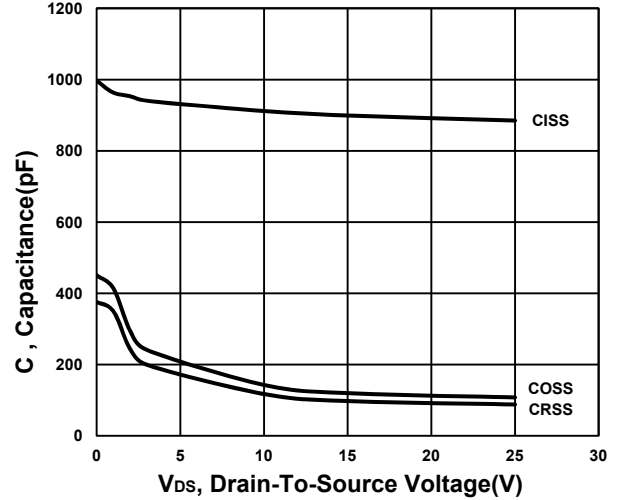
Transfer Characteristics



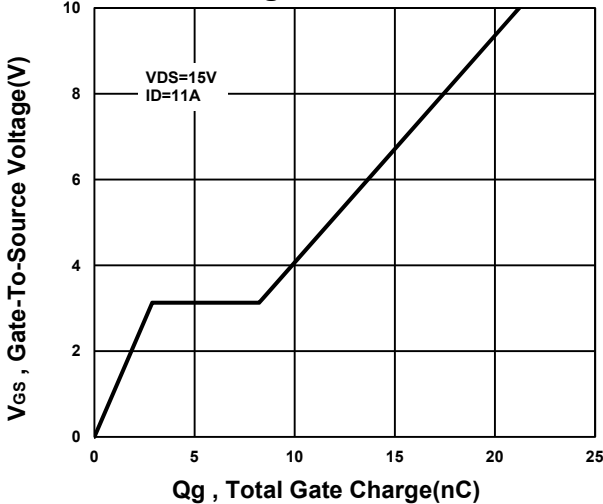
On-Resistance VS Temperature



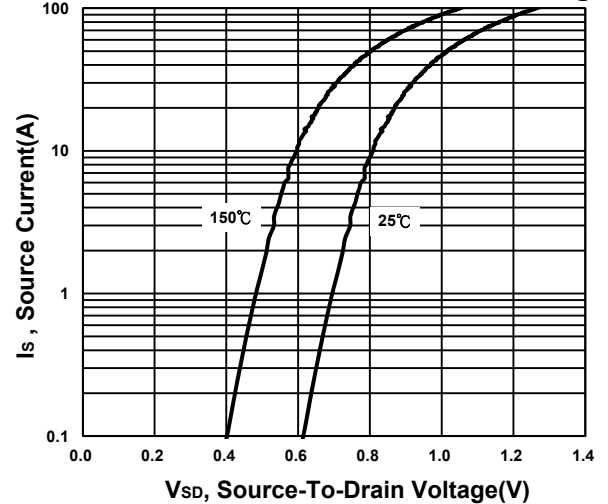
Capacitance Characteristic



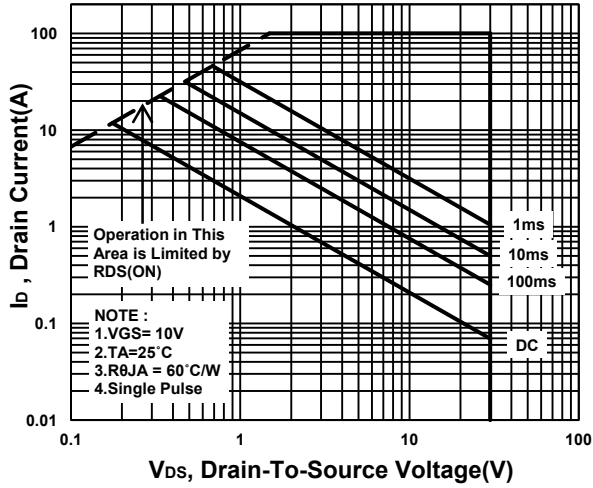
Gate charge Characteristics



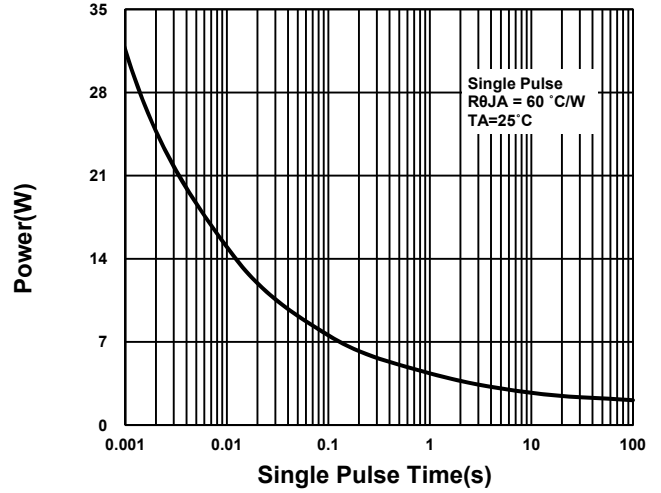
Source-Drain Diode Forward Voltage



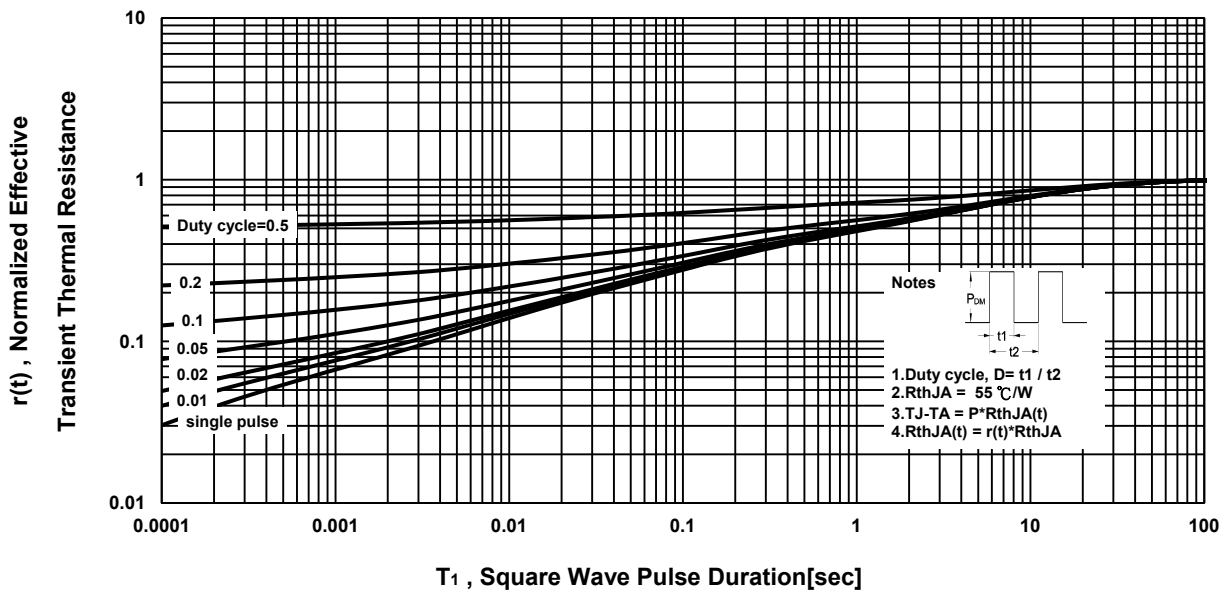
Safe Operating Area



Single Pulse Maximum Power Dissipation



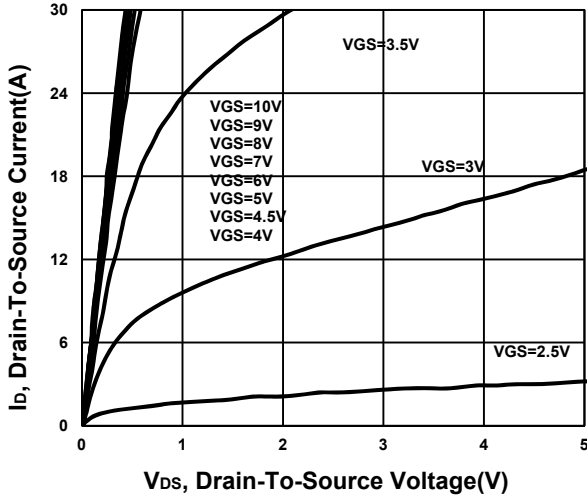
Transient Thermal Response Curve



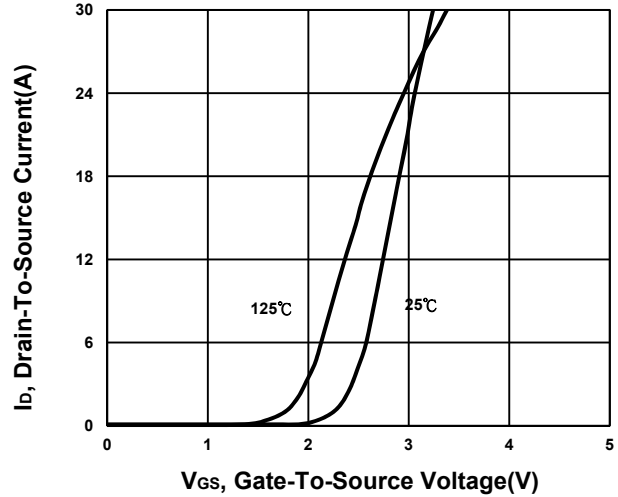
TYPICAL PERFORMANCE CHARACTERISTICS

Q1

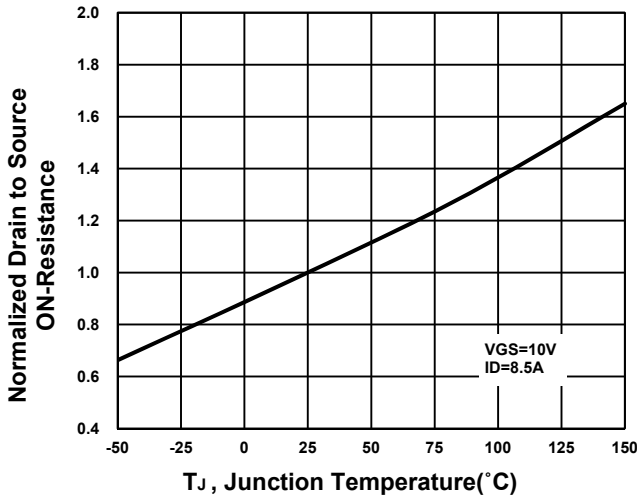
Output Characteristics



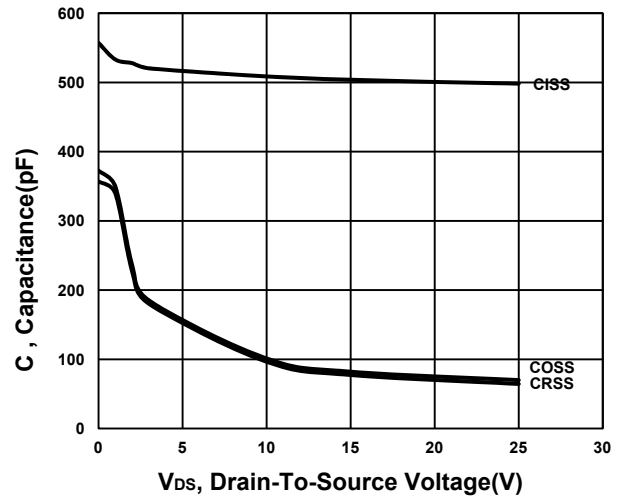
Transfer Characteristics



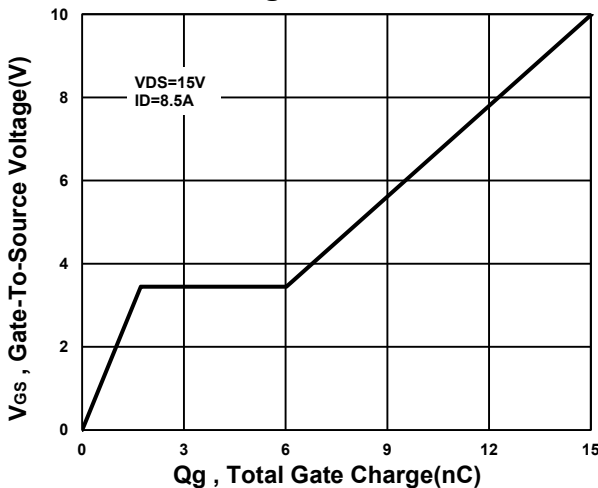
On-Resistance VS Temperature



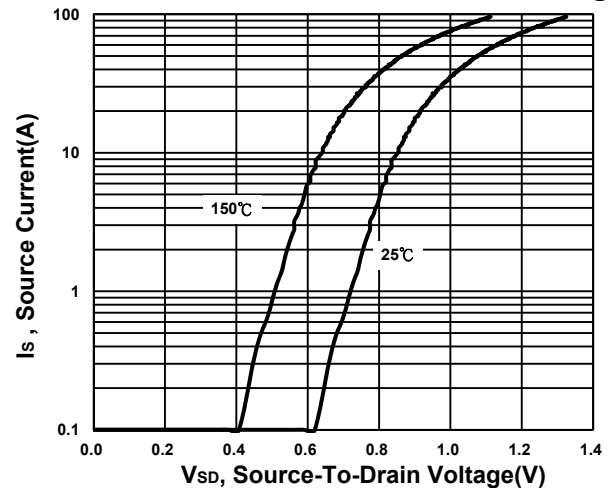
Capacitance Characteristic



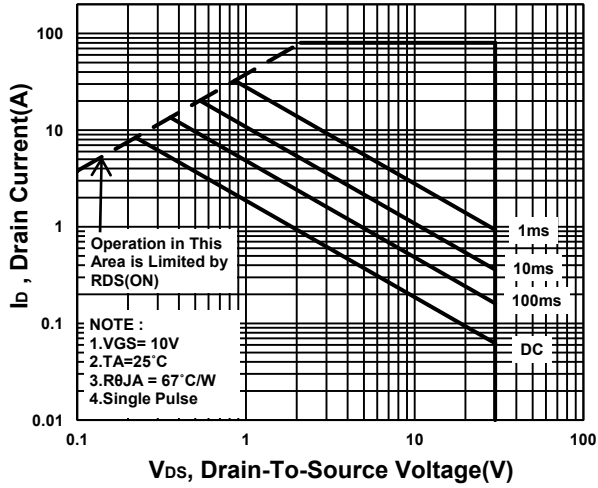
Gate charge Characteristics



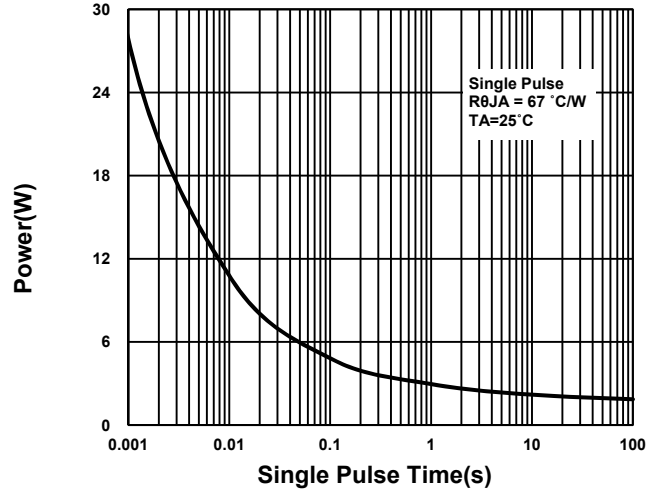
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

